

VN2222LLG

Small Signal MOSFET 150 mAmps, 60 Volts

N-Channel TO-92

Features

- This is a Pb-Free Device*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	60	Vdc
Drain-Gate Voltage ($R_{GS} = 1.0 \text{ M}\Omega$)	V_{DGR}	60	Vdc
Gate-Source Voltage	V_{GS}	± 20	Vdc
– Continuous	V_{GSM}	± 40	Vpk
– Non-repetitive ($t_p \leq 50 \mu s$)			
Drain Current	I_D	150	mAdc
– Continuous	I_{DM}	1000	
– Pulsed			
Total Power Dissipation @ $T_A = 25^\circ\text{C}$	P_D	400	mW
Derate above 25°C		3.2	mW/ $^\circ\text{C}$
Operating and Storage Temperature Range	T_J, T_{stg}	-55 to $+150$	$^\circ\text{C}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	312.5	$^\circ\text{C}/\text{W}$
Maximum Lead Temperature for Soldering Purposes, 1/16" from case for 10 seconds	T_L	300	$^\circ\text{C}$

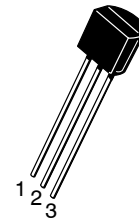
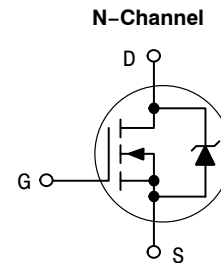
*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



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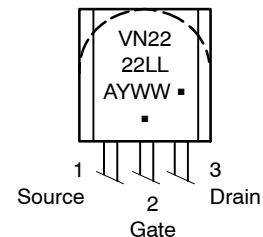
<http://onsemi.com>

150 mA, 60 V
 $R_{DS(on)} = 7.5 \Omega$



TO-92
CASE 29
STYLE 22

MARKING DIAGRAM & PIN ASSIGNMENT



A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb-Free Package
(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

VN2222LLG

ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
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OFF CHARACTERISTICS

Drain-Source Breakdown Voltage ($V_{GS} = 0$, $I_D = 100 \mu\text{Adc}$)	$V_{(BR)DSS}$	60	–	Vdc
Zero Gate Voltage Drain Current ($V_{DS} = 48 \text{ Vdc}$, $V_{GS} = 0$) ($V_{DS} = 48 \text{ Vdc}$, $V_{GS} = 0$, $T_J = 125^\circ\text{C}$)	I_{DSS}	– –	10 500	μAdc
Gate-Body Leakage Current, Forward ($V_{GSF} = 30 \text{ Vdc}$, $V_{DS} = 0$)	I_{GSSF}	–	–100	nAdc

ON CHARACTERISTICS (Note 1)

Gate Threshold Voltage ($V_{DS} = V_{GS}$, $I_D = 1.0 \text{ mAdc}$)	$V_{GS(th)}$	0.6	2.5	Vdc
Static Drain-Source On-Resistance ($V_{GS} = 10 \text{ Vdc}$, $I_D = 0.5 \text{ Adc}$) ($V_{GS} = 10 \text{ Vdc}$, $I_D = 0.5 \text{ Vdc}$, $T_C = 125^\circ\text{C}$)	$r_{DS(on)}$	– –	7.5 13.5	Ω
Drain-Source On-Voltage ($V_{GS} = 5.0 \text{ Vdc}$, $I_D = 200 \text{ mAdc}$) ($V_{GS} = 10 \text{ Vdc}$, $I_D = 500 \text{ mAdc}$)	$V_{DS(on)}$	– –	1.5 3.75	Vdc
On-State Drain Current ($V_{GS} = 10 \text{ Vdc}$, $V_{DS} \geq 2.0 V_{DS(on)}$)	$I_{D(on)}$	750	–	mA
Forward Transconductance ($V_{DS} = 10 \text{ Vdc}$, $I_D = 500 \text{ mAdc}$)	g_{fs}	100	–	μmhos

DYNAMIC CHARACTERISTICS

Input Capacitance	$(V_{DS} = 25 \text{ Vdc}$, $V_{GS} = 0$, $f = 1.0 \text{ MHz})$	C_{iss}	–	60	pF
Output Capacitance		C_{oss}	–	25	
Reverse Transfer Capacitance		C_{rss}	–	5.0	

SWITCHING CHARACTERISTICS (Note 1)

Turn-On Delay Time	$(V_{DD} = 15 \text{ Vdc}$, $I_D = 600 \text{ mA}$, $R_{gen} = 25 \Omega$, $R_L = 23 \Omega$)	t_{on}	–	10	ns
Turn-Off Delay Time		t_{off}	–	10	

1. Pulse Test: Pulse Width $\leq 300 \mu\text{s}$, Duty Cycle $\leq 2.0\%$.

ORDERING INFORMATION

Device	Package	Shipping [†]
VN2222LLG	TO-92 (Pb-Free)	1000 Unit / Box

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

VN2222LLG

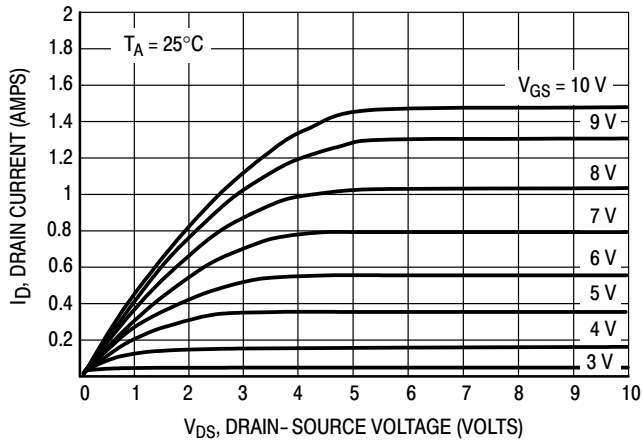


Figure 1. Ohmic Region

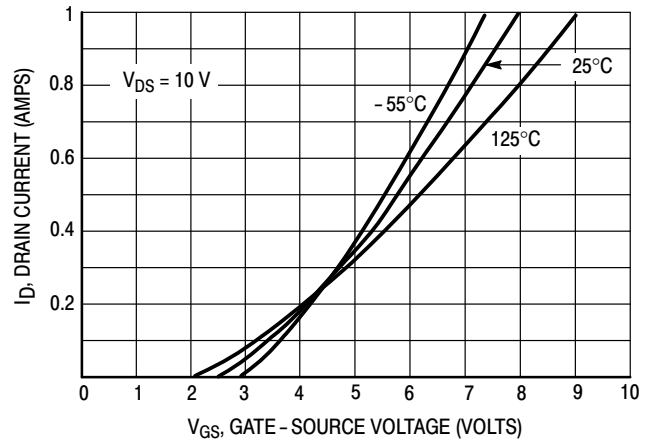


Figure 2. Transfer Characteristics

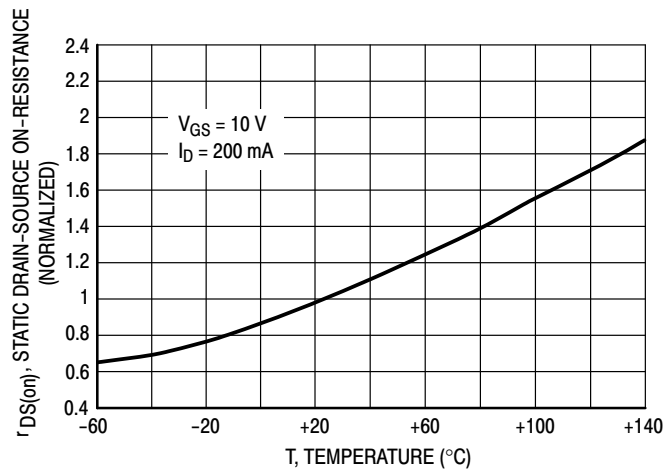


Figure 3. Temperature versus Static Drain-Source On-Resistance

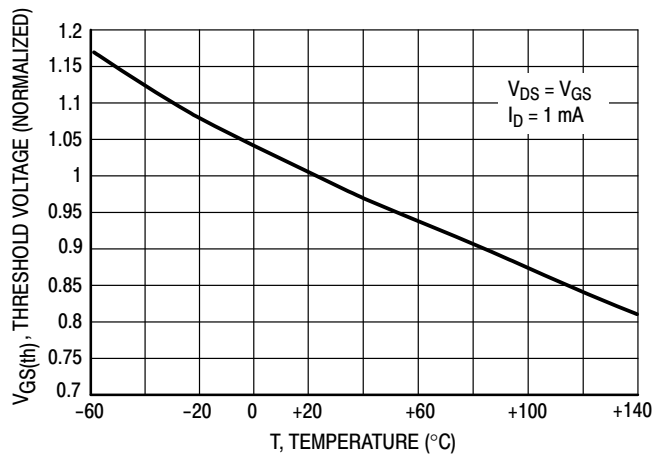
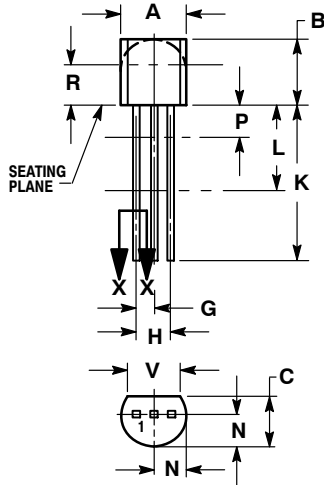


Figure 4. Temperature versus Gate Threshold Voltage

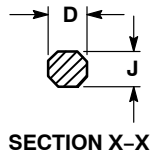
VN2222LLG

PACKAGE DIMENSIONS

TO-92
CASE 29-11
ISSUE AM



STRAIGHT LEAD
BULK PACK

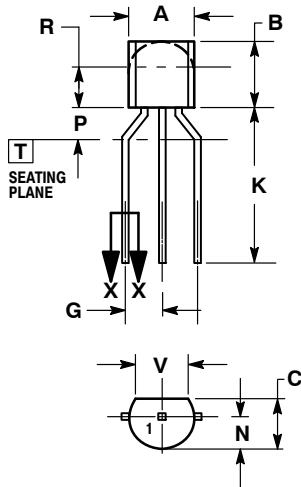


SECTION X-X

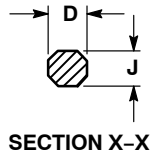
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.175	0.205	4.45	5.20
B	0.170	0.210	4.32	5.33
C	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
H	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500	---	12.70	---
L	0.250	---	6.35	---
N	0.080	0.105	2.04	2.66
P	---	0.100	---	2.54
R	0.115	---	2.93	---
V	0.135	---	3.43	---



BENT LEAD
TAPE & REEL
AMMO PACK



SECTION X-X


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

DIM	MILLIMETERS	
	MIN	MAX
A	4.45	5.20
B	4.32	5.33
C	3.18	4.19
D	0.40	0.54
G	2.40	2.80
J	0.39	0.50
K	12.70	---
N	2.04	2.66
P	1.50	4.00
R	2.93	---
V	3.43	---

STYLE 22:

1. SOURCE
2. GATE
3. DRAIN

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